

Product Change Notification - KSRA-24QRXM272

Date: 30 Oct 2017

Product Category:

Notification subject: CCB 3134 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 200K wafer technology available in 40L UQFN package at NSEB assembly site

Notification text: **PCN Status:**
Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 200K wafer technology available in 40L UQFN package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	UTAC Thai Limited LTD (NSEB) Assembly Site	UTAC Thai Limited LTD (NSEB) Assembly Site
Wire material	Au Wire	CuPdAu Wire
Die attach material	8600	8600
Molding compound material	G700LTD	G700LTD
Lead frame material	EFTEC-64T	EFTEC-64T

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and qualify CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

March 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	October 2017					-->	March 2018				
	40	41	42	43	44		09	10	11	12	13
Workweek											
Initial PCN Issue Date					X						
Qual Report Availability											X
Final PCN Issue Date											X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:

October 30, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_KSRA-24QRXM272_Qual Plan.pdf](#)
- [PCN_KSRA-24QRXM272_Affected CPN.pdf](#)
- [PCN_KSRA-24QRXM272_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-24QRXM272
CATALOG_PART_NBR
HA7620-I/MV
HA7620T-I/MV
HA7621-I/MV
HA7621T-I/MV
PIC16F1517-E/MV
PIC16F1517-I/MV
PIC16F1517T-I/MV
PIC16F1519-E/MV
PIC16F1519-I/MV
PIC16F1519T-I/MV
PIC16F1717-E/MV
PIC16F1717-I/MV
PIC16F1717T-I/MV
PIC16F1719-E/MV
PIC16F1719-I/MV
PIC16F1719T-I/MV
PIC16F1777-E/MV
PIC16F1777-I/MV
PIC16F1777T-I/MV
PIC16F1779-E/MV
PIC16F1779-I/MV
PIC16F1779T-E/MV
PIC16F1779T-I/MV
PIC16F1784-E/MV
PIC16F1784-I/MV
PIC16F1784T-E/MV
PIC16F1784T-I/MV
PIC16F1787-E/MV
PIC16F1787-I/MV
PIC16F1787T-I/MV
PIC16F1789-E/MV
PIC16F1789-I/MV
PIC16F1789T-E/MV
PIC16F1789T-I/MV
PIC16F1789T-I/MV020
PIC16F1789T-I/MV021
PIC16F1789T-I/MV022
PIC16F1934-E/MV
PIC16F1934-I/MV
PIC16F1934T-E/MV
PIC16F1934T-I/MV
PIC16F1937-E/MV
PIC16F1937-I/MV

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PCN_KSRA-24QRXM272
CATALOG_PART_NBR
PIC16F1937T-I/MV
PIC16F1939-E/MV
PIC16F1939-I/MV
PIC16F1939T-E/MV
PIC16F1939T-I/MV
PIC16F707-I/MV
PIC16F724-E/MV
PIC16F724-I/MV
PIC16F724T-I/MV
PIC16F727-E/MV
PIC16F727-I/MV
PIC16F727T-I/MV
PIC16LF1517-E/MV
PIC16LF1517-I/MV
PIC16LF1517T-I/MV
PIC16LF1519-E/MV
PIC16LF1519-I/MV
PIC16LF1519T-I/MV
PIC16LF1567-E/MV
PIC16LF1567-I/MV
PIC16LF1567T-I/MV
PIC16LF1717-E/MV
PIC16LF1717-I/MV
PIC16LF1717T-I/MV
PIC16LF1719-E/MV
PIC16LF1719-I/MV
PIC16LF1719T-I/MV
PIC16LF1777-E/MV
PIC16LF1777-I/MV
PIC16LF1777T-I/MV
PIC16LF1779-E/MV
PIC16LF1779-I/MV
PIC16LF1779T-E/MV
PIC16LF1779T-I/MV
PIC16LF1784-E/MV
PIC16LF1784-I/MV
PIC16LF1784T-I/MV
PIC16LF1787-E/MV
PIC16LF1787-I/MV
PIC16LF1787T-I/MV
PIC16LF1789-E/MV
PIC16LF1789-I/MV
PIC16LF1789T-I/MV

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-24QRXM272
CATALOG_PART_NBR
PIC16LF1904-E/MV
PIC16LF1904-I/MV
PIC16LF1904T-I/MV
PIC16LF1904T-I/MV022
PIC16LF1907-E/MV
PIC16LF1907-I/MV
PIC16LF1907T-I/MV
PIC16LF1934-E/MV
PIC16LF1934-I/MV
PIC16LF1934T-I/MV
PIC16LF1937-E/MV
PIC16LF1937-I/MV
PIC16LF1937T-I/MV
PIC16LF1939-E/MV
PIC16LF1939-I/MV
PIC16LF1939T-I/MV
PIC16LF724-E/MV
PIC16LF724-I/MV
PIC16LF724T-I/MV
PIC16LF727-E/MV
PIC16LF727-I/MV
PIC16LF727T-I/MV
PIC18F43K20-E/MV
PIC18F43K20-I/MV
PIC18F43K20T-I/MV
PIC18F43K22-E/MV
PIC18F43K22-I/MV
PIC18F43K22T-I/MV
PIC18F44K20-E/MV
PIC18F44K20-I/MV
PIC18F44K20T-I/MV
PIC18F44K22-E/MV
PIC18F44K22-I/MV
PIC18F44K22T-I/MV
PIC18F45K20-E/MV
PIC18F45K20-I/MV
PIC18F45K20T-I/MV
PIC18F45K22-E/MV
PIC18F45K22-I/MV
PIC18F45K22T-I/MV
PIC18F45K50-E/MV
PIC18F45K50-I/MV
PIC18F45K50T-I/MV

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-24QRXM272
CATALOG_PART_NBR
PIC18F46K20-E/MV
PIC18F46K20-I/MV
PIC18F46K20T-I/MV
PIC18F46K22-E/MV
PIC18F46K22-I/MV
PIC18F46K22T-E/MV
PIC18F46K22T-E/MV025
PIC18F46K22T-E/MV026
PIC18F46K22T-E/MV027
PIC18F46K22T-E/MV028
PIC18F46K22T-E/MV029
PIC18F46K22T-E/MV030
PIC18F46K22T-I/MV
PIC18LF43K22-E/MV
PIC18LF43K22-I/MV
PIC18LF43K22T-I/MV
PIC18LF44K22-E/MV
PIC18LF44K22-I/MV
PIC18LF44K22T-I/MV
PIC18LF45K22-E/MV
PIC18LF45K22-I/MV
PIC18LF45K22T-I/MV
PIC18LF45K50-E/MV
PIC18LF45K50-I/MV
PIC18LF45K50T-I/MV
PIC18LF46K22-E/MV
PIC18LF46K22-I/MV
PIC18LF46K22T-I/MV
PIC18LF46K22T-I/MV020
PIC18LF46K22T-I/MV022
PIC18LF46K22T-I/MVC03